

Welcome to [E-XFL.COM](#)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	F ² MC-8L
Core Size	8-Bit
Speed	10MHz
Connectivity	EBI/EMI, Serial I/O, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	53
Program Memory Size	16KB (16K x 8)
Program Memory Type	Mask ROM
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 6V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-BQFP
Supplier Device Package	64-QFP (14x20)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb89635rpf-g-1461

8-bit Proprietary Microcontroller

CMOS

F²MC-8L MB89630R Series

MB89635R/636R/637R/P637/PV630

■ OUTLINE

The MB89630R series has been developed as a general-purpose version of the F²MC*-8L family consisting of proprietary 8-bit, single-chip microcontrollers.

In addition to a compact instruction set, the microcontrollers contain a variety of peripheral functions such as dual-clock control system, five operating speed control stages, a UART, timers, a PWM timer, a serial interface, an A/D converter, an external interrupt, and a watch prescaler.

* : F²MC is the abbreviation for Fujitsu Flexible Microcontroller.

■ FEATURES

- High-speed operating capability at low voltage
- Minimum execution time: 0.4 μ s@3.5 V, 0.8 μ s@2.7 V
- F²MC-8L family CPU core

Instruction set optimized for controllers	{	<ul style="list-style-type: none"> Multiplication and division instructions 16-bit arithmetic operations Test and branch instructions Bit manipulation instructions, etc.
---	---	---

- Five types of timers
 - 8-bit PWM timer: 2 channels (Also usable as a reload timer)
 - 8-bit pulse-width count timer (Continuous measurement capable, applicable to remote control, etc.)
 - 16-bit timer/counter
 - 21-bit timebase timer

(Continued)

For the information for microcontroller supports, see the following web site.

<http://edevic.fujitsu.com/micom/en-support/>

■ PRODUCT LINEUP

Part number Item	MB89635R	MB89636R	MB89637R	MB89P637	MB89PV630
Classification	Mass-produced products (mask ROM products)			One-time PROM product	Piggyback/ evaluation product (for evaluation and development)
ROM size	16 K × 8 bits (internal mask ROM)	24 K × 8 bits (internal mask ROM)	32 K × 8 bits (internal mask ROM)	32 K × 8 bits (Internal PROM, to be programmed with general- purpose EPROM programmer)	32 K × 8 bits (external ROM)
RAM size	512 × 8 bits	768 × 8 bits	1024 × 8 bits	1024 × 8 bits	1024 × 8 bits
CPU functions	The number of instructions: 136 Instruction bit length: 8 bits Instruction length: 1 to 3 bytes Data bit length: 1, 8, 16 bits Minimum execution time: 0.4 μs/10 MHz, 61 μs@32.768 kHz Interrupt processing time: 3.6 to 57.6 μs/10 MHz, 562.5 μs@32.768 kHz				
Ports	Input ports: 5 (All also serve as peripherals.) Output ports (N-ch open-drain): 8 (All also serve as peripherals.) I/O ports (N-ch open-drain): 4 (All also serve as peripherals.) Output ports (CMOS): 8 (All also serve as bus control.) I/O ports (CMOS): 28 (27 ports also serve as bus pins and peripherals.) Total: 53				
Watch timer	21 bits × 1 (in main clock)/15 bits × 1 (at 32.768 kHz)				
8-bit PWM timer	8-bit reload timer operation (toggled output capable, operating clock cycle: 0.4 μs to 3.3 ms) × 2 channels 7/8-bit resolution PWM operation (conversion cycle: 51.2 μs to 839 ms) × 2 channels				
8-bit pulse width count timer	8-bit timer operation (overflow output capable, operating clock cycle: 0.4 to 12.8 μs) 8-bit reload timer operation (toggled output capable, operating clock cycle: 0.4 to 12.8 μs) 8-bit pulse width measurement operation (capable of continuous measurement, and measurement of "H" pulse width/ "L" pulse width/ from ↑ to ↑/from ↓ to ↓)				
16-bit timer/counter	16-bit timer operation (operating clock cycle: 0.4 μs) 16-bit event counter operation (rising edge/falling edge/both edge selectable)				
8-bit serial I/O	8 bits LSB first/MSB first selectable One clock selectable from four transfer clocks (one external shift clock, three internal shift clocks: 0.8 μs, 3.2 μs, 12.8 μs)				
UART	Capable of switching two I/O systems by software Transfer data length (6, 7, and 8 bits) Transfer rate (300 to 62500 bps. at 10 MHz oscillation)				
10-bit A/D converter	10-bit resolution × 8 channels A/D conversion mode (conversion time: 13.2 μs) Sense mode (conversion time: 7.2 μs) Capable of continuous activation by an external activation or an internal timer				

(Continued)

MB89630R Series

(Continued)

Part number Item	MB89635R	MB89636R	MB89637R	MB89P637	MB89PV630
External interrupt input	4 independent channels (edge selection, interrupt vector, source flag). Rising edge/falling edge selectable Used also for wake-up from stop/sleep mode. (Edge detection is also permitted in stop mode.)				
Standby mode	Sleep mode, stop mode, watch mode, and subclock mode				
Process	CMOS				
Operating voltage*	2.2 V to 6.0 V			2.7 V to 6.0 V	
EPROM for use					MBM27C256A-20CZ MBM27C256A-20TV

* : Varies with conditions such as the operating frequency. (See section “■ Electrical Characteristics.”)
In the case of the MB89PV630, the voltage varies with the restrictions of the EPROM for use.

■ PACKAGE AND CORRESPONDING PRODUCTS

Package	MB89635R	MB89636R MB89637R	MB89P637	MB89PV630
DIP-64P-M01	○	○	○	×
FPT-64P-M06	○	○	○	×
FPT-64P-M23	○	○	×	×
MQP-64C-P01	×	×	×	○
MDP-64C-P02	×	×	×	○

○ : Available ×: Not available

Note: For more information about each package, see section “■ Package Dimensions.”

■ PIN DESCRIPTION

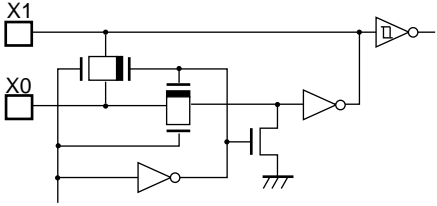
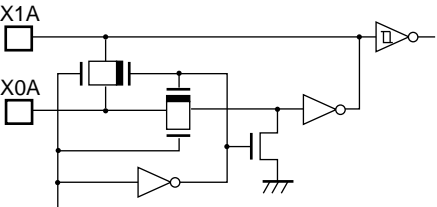
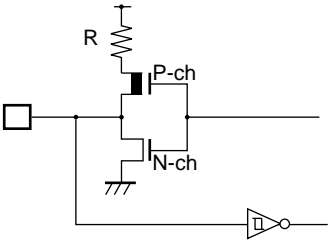
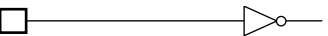
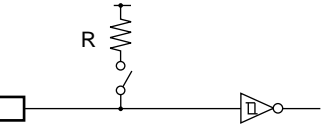
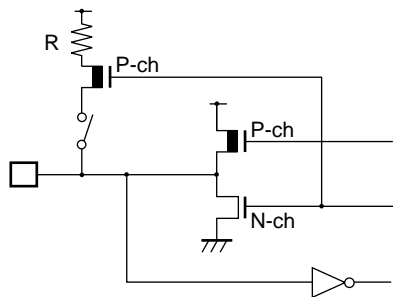
Pin no.			Pin name	Circuit type	Function
SH-DIP ^{*1} MDIP ^{*2}	QFP2 ^{*3}	QFP1 ^{*4} MQFP ^{*5}			
30	22	23	X0	A	Main clock crystal oscillator pins
31	23	24	X1		
28	20	21	MOD0	D	Operating mode selection pins Connect directly to V _{CC} or V _{SS} .
29	21	22	MOD1		
27	19	20	RST	C	Reset I/O pin This pin is an N-ch open-drain output type with a pull-up resistor, and a hysteresis input type. “L” is output from this pin by an internal reset source. The internal circuit is initialized by the input of “L”.
56 to 49	48 to 41	49 to 42	P00/AD0 to P07/AD7	F	General-purpose I/O ports When an external bus is used, these ports function as the multiplex pins of the lower address output and the data I/O.
48 to 41	40 to 33	41 to 34	P10/A08 to P17/A157	F	General-purpose I/O ports When an external bus is used, these ports function as an upper address output.
40	32	33	P20/BUFC	H	General-purpose output port When an external bus is used, this port can also be used as a buffer control output by setting the BCTR.
39	31	32	P21/HAK	H	General-purpose output port When an external bus is used, this port can also be used as a hold acknowledge by setting the BCTR.
38	30	31	P22/HRQ	F	General-purpose output port When an external bus is used, this port can also be used as a hold request input by setting the BCTR.
37	29	30	P23/RDY	F	General-purpose output port When an external bus is used, this port functions as a ready input.
36	28	29	P24/CLK	H	General-purpose output port When an external bus is used, this port functions as a clock output.
35	27	28	P25/WR	H	General-purpose output port When an external bus is used, this port functions as a write signal output.
34	26	27	P26/RD	H	General-purpose output port When an external bus is used, this port functions as a read signal output.

*1: DIP-64P-M01
*2: MDP-64C-P02
*3: FPT-64P-M23

*4: FPT-64P-M06
*5: MQP-M64C-P01

(Continued)

■ I/O CIRCUIT TYPE

Type	Circuit	Remarks
A	 <p>Standby control signal</p>	<ul style="list-style-type: none"> Crystal or ceramic oscillation type (main clock) External clock input selection versions of MB89PV630, MB89P637, MB89635R, MB89636R, and MB89637R At an oscillation feedback resistor of approximately 1 MΩ@5.0 V
B	 <p>Standby control signal</p>	<ul style="list-style-type: none"> Crystal or ceramic oscillation type (subclock) MB89PV630, MB89P637, MB89635R, MB89636R, and MB89637R with dual-clock system At an oscillation feedback resistor of approximately 4.5 MΩ@5.0 V
C		<ul style="list-style-type: none"> At an output pull-up resistor (P-ch) of approximately 50 kΩ@5.0 V Hysteresis input
D		
E		<ul style="list-style-type: none"> Hysteresis input Pull-up resistor optional (except P70 and P71)
F		<ul style="list-style-type: none"> CMOS output CMOS input Pull-up resistor optional (except P22 and P23)

(Continued)

■ HANDLING DEVICES

1. Preventing Latchup

Latchup may occur on CMOS ICs if voltage higher than V_{CC} or lower than V_{SS} is applied to input and output pins other than medium- and high-voltage pins or if higher than the voltage which shows on “1. Absolute Maximum Ratings” in section “■ Electrical Characteristics” is applied between V_{CC} and V_{SS} .

When latchup occurs, power supply current increases rapidly and might thermally damage elements. When using, take great care not to exceed the absolute maximum ratings.

Also, take care to prevent the analog power supply (AV_{CC} and AVR) and analog input from exceeding the digital power supply (V_{CC}) when the analog system power supply is turned on and off.

2. Treatment of Unused Input Pins

Leaving unused input pins open could cause malfunctions. They should be connected to a pull-up or pull-down resistor.

3. Treatment of Power Supply Pins on Microcontrollers with A/D and D/A Converters

Connect to be $AV_{CC} = DAVC = V_{CC}$ and $AV_{SS} = AVR = V_{SS}$ even if the A/D and D/A converters are not in use.

4. Treatment of N.C. Pins

Be sure to leave (internally connected) N.C. pins open.

5. Power Supply Voltage Fluctuations

Although V_{CC} power supply voltage is assured to operate within the rated range, a rapid fluctuation of the voltage could cause malfunctions, even if it occurs within the rated range. Stabilizing voltage supplied to the IC is therefore important. As stabilization guidelines, it is recommended to control power so that V_{CC} ripple fluctuations (P-P value) will be less than 10% of the standard V_{CC} value at the commercial frequency (50 Hz to 60 Hz) and the transient fluctuation rate will be less than 0.1 V/ms at the time of a momentary fluctuation such as when power is switched.

6. Precautions when Using an External Clock

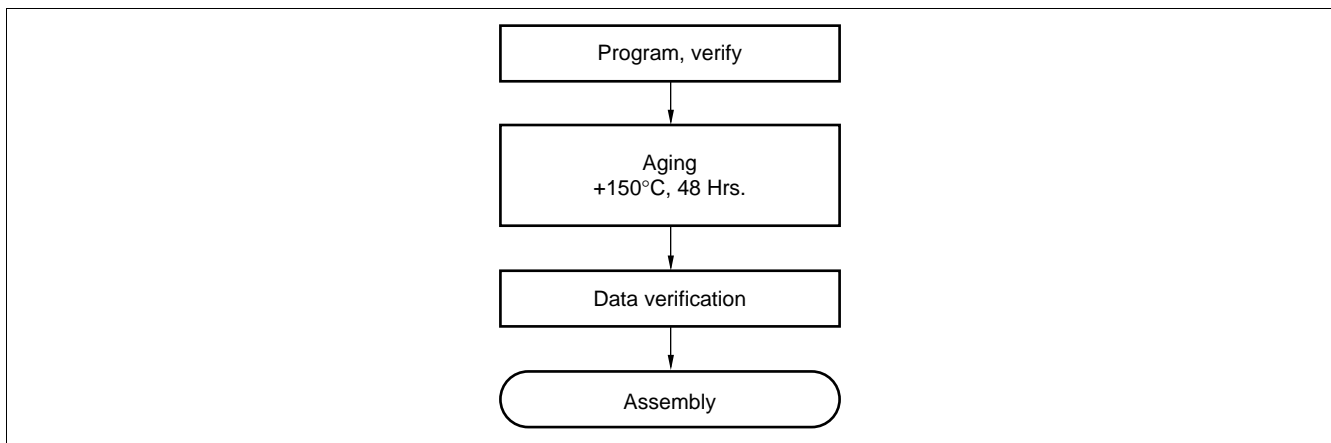
When an external clock is used, oscillation stabilization time is required even for power-on reset (option selection) and wake-up from stop mode.

- **Programming procedure**

- (1) Set the EPROM programmer to the MBM27C256A.
- (2) Load program data into the EPROM programmer at 0007_H to 7FFF_H. (Note that addresses 8000_H to FFFF_H in the operating mode assign to 0000_H to 7FFF_H in EPROM mode).
- (3) Load option data into addresses 0000_H to 0006_H of the EPROM programmer.
(For information about each corresponding option, see "8. OTPROM Option Bit Map".)
- (4) Program with the EPROM programmer.

4. Recommended Screening Conditions

High-temperature aging is recommended as the pre-assembly screening procedure for a product with a blanked OTPROM microcomputer program.



5. Programming Yield

All bits cannot be programmed at Fujitsu shipping test to a blanked OTPROM microcomputer, due to its nature. For this reason, a programming yield of 100% cannot be assured at all times.

MB89630R Series

2. Registers

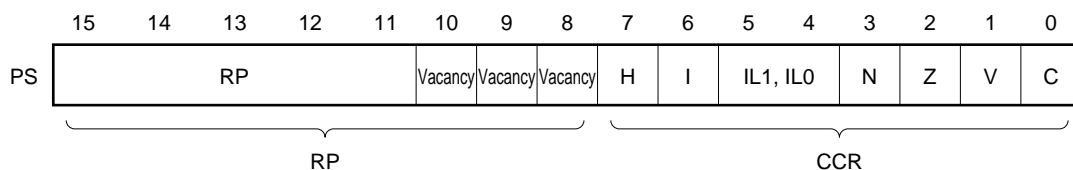
The F²MC-8L family has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The following dedicated registers are provided:

Program counter (PC):	A 16-bit register for indicating the instruction storage positions
Accumulator (A):	A 16-bit temporary register for storing arithmetic operations, etc. When the instruction is an 8-bit data processing instruction, the lower byte is used.
Temporary accumulator (T):	A16-bit register which performs arithmetic operations with the accumulator When the instruction is an 8-bit data processing instruction, the lower byte is used.
Index register (IX):	A16-bit register for index modification
Extra pointer (EP):	A16-bit pointer for indicating a memory address
Stack pointer (SP):	A16-bit register for indicating a stack area
Program status (PS):	A16-bit register for storing a register pointer, a condition code

16 bits		Initial value
PC	: Program counter	FFFD _H
A	: Accumulator	Indeterminate
T	: Temporary accumulator	Indeterminate
IX	: Index register	Indeterminate
EP	: Extra pointer	Indeterminate
SP	: Stack pointer	Indeterminate
PS	: Program status	I-flag = 0, IL1, IL0 = 11 The other bit values are indeterminate.

The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and the lower 8 bits for use as a condition code register (CCR). (See the diagram below.)

• Structure of the program status register



■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

(AV_{SS} = V_{SS} = 0.0 V)

Parameter	Symbol	Value		Unit	Remarks
		Min.	Max.		
Power supply voltage	V _{CC}	V _{SS} – 0.3	V _{SS} + 7.0	V	*
	AV _{CC}	V _{SS} – 0.3	V _{SS} + 7.0	V	*
A/D converter reference input voltage	AVR	V _{SS} – 0.3	V _{SS} + 7.0	V	AVR must not exceed "AV _{CC} + 0.3 V".
Input voltage	V _I	V _{SS} – 0.3	V _{CC} + 0.3	V	Except P50 to P53
	V _{I2}	V _{SS} – 0.3	V _{SS} + 7.0	V	P50 to P53
Output voltage	V _O	V _{SS} – 0.3	V _{CC} + 0.3	V	Except P50 to P53
	V _{O2}	V _{SS} – 0.3	V _{SS} + 7.0	V	P50 to P53
"L" level maximum output current	I _{OL}	—	20	mA	
"L" level average output current	I _{OLAV}	—	4	mA	Average value (operating current × operating rate)
"L" level total maximum output current	ΣI _{OL}	—	100	mA	
"L" level total average output current	ΣI _{OLAV}	—	40	mA	Average value (operating current × operating rate)
"H" level maximum output current	I _{OH}	—	–20	mA	
"H" level average output current	I _{OHAV}	—	–4	mA	Average value (operating current × operating rate)
"H" level total maximum output current	ΣI _{OH}	—	–50	mA	
"H" level total average output current	ΣI _{OHAV}	—	–20	mA	Average value (operating current × operating rate)
Power consumption	P _D	—	500	mW	
Operating temperature	T _A	–40	+85	°C	
Storage temperature	T _{stg}	–55	+150	°C	

* : Use AV_{CC} and V_{CC} set at the same voltage.

Take care so that AV_{CC} does not exceed V_{CC}, such as when power is turned on.

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

MB89630R Series

3. DC Characteristics

($V_{CC} = 5.0\text{ V}$, $V_{SS} = 0.0\text{ V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

Parameter	Symbol	Pin name	Condition	Value			Unit	Remarks
				Min.	Typ.	Max.		
“H” level input voltage	V_{IH1}	P00 to P07, P10 to P17, P22, P23, P31, P34, P37, P41, P43, P51 to P53	—	$0.7 V_{CC}$	—	$V_{CC} + 0.3$	V	P51 to P53 with pull-up resistor
	V_{IH2}	P51 to P53		$0.7 V_{CC}$	—	$V_{SS} + 6.0$	V	Without pull-up resistor
	V_{IHS}	\overline{RST} , MOD0, MOD1, P30, P32, P33, P35, P36, P40, P42, P50, P72 to P74		$0.8 V_{CC}$	—	$V_{CC} + 0.3$	V	P50 with pull-up resistor
	V_{IHS2}	P50, P70, P71		$0.8 V_{CC}$	—	$V_{SS} + 6.0$	V	Without pull-up resistor
“L” level input voltage	V_{IL}	P00 to P07, P10 to P17, P22, P23, P31, P34, P37, P41, P43	—	$V_{SS} - 0.3$	—	$0.3 V_{CC}$	V	
	V_{ILS}	P30, P32, P33, P35, P36, P40, P42, P50 to P53, P70 to P74, \overline{RST} , MOD0, MOD1		$V_{SS} - 0.3$	—	$0.2 V_{CC}$	V	
Open-drain output pin application voltage	V_D	P50 to P53	—	$V_{SS} - 0.3$	—	$V_{SS} + 6.0$	V	
“H” level output voltage	V_{OH}	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P43	$I_{OH} = -2.0\text{ mA}$	4.0	—	—	V	
“L” level output voltage	V_{OL}	P00 to P07, P10 to P17, P20 to P27, P30 to P37, P40 to P43, P50 to P53, P60 to P67, \overline{RST}	$I_{OL} = 4.0\text{ mA}$	—	—	0.4	V	
Input leakage current (Hi-z output leakage current)	I_{LI}	P00 to P07, P10 to P17, P20 to P23, P30 to P37, P40 to P43, P50 to P53, P70 to P74, MOD0, MOD1	$0.0\text{ V} < V_I < V_{CC}$	—	—	± 5	μA	Without pull-up resistor

(Continued)

MB89630R Series

(Continued)

($AV_{CC} = V_{CC} = 5.0\text{ V}$, $AV_{SS} = V_{SS} = 0.0\text{ V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

Parameter	Symbol	Pin name	Condition	Value			Unit	Remarks
				Min.	Typ.	Max.		
Power supply current*1	I_A	AV_{CC}	$F_{CH} = 10\text{ MHz}$, when A/D conversion operates.	—	6	—	mA	
	I_{AH}		$F_{CH} = 10\text{ MHz}$, $T_A = +25^\circ\text{C}$, when A/D conversion in a stop.	—	—	1	μA	
Input capacitance	C_{IN}	Other than AV_{CC} , AV_{SS} , V_{CC} , and V_{SS}	$f = 1\text{ MHz}$	—	10	—	pF	

*1: The power supply current is measured at the external clock.

In the case of the MB89PV630, the current consumed by the connected EPROM and ICE is not counted.

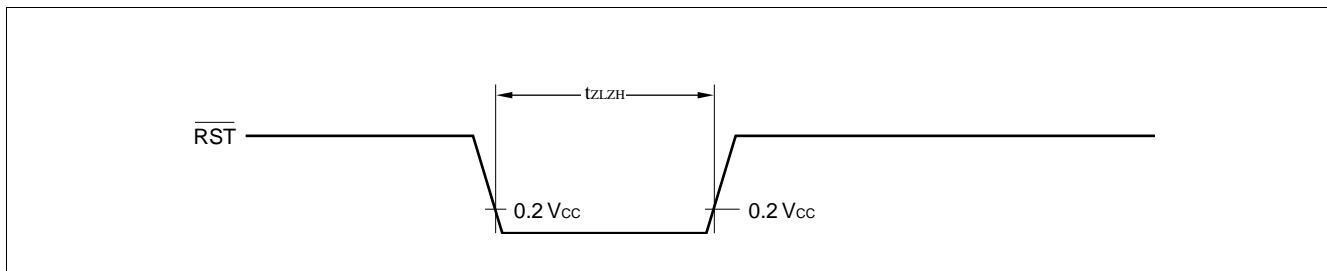
*2: For information on t_{inst} , see “(4) Instruction Cycle” in “4. AC Characteristics”.

4. AC Characteristics

(1) Reset Timing

($V_{CC} = 5.0\text{ V} \pm 10\%$, $AV_{SS} = V_{SS} = 0.0\text{ V}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$)

Parameter	Symbol	Condition	Value		Unit	Remarks
			Min.	Max.		
$\overline{\text{RST}}$ “L” pulse width	t_{ZLZH}	—	$48\ t_{HCYL}$	—	ns	



(4) Instruction Cycle

Parameter	Symbol	Value (typical)	Unit	Remarks
Instruction cycle (minimum execution time)	t_{inst}	$4/F_{\text{CH}}, 8/F_{\text{CH}}, 16/F_{\text{CH}}, 64/F_{\text{CH}}$	μs	$(4/F_{\text{CH}}) t_{\text{inst}} = 0.4 \mu\text{s}$, operating at $F_{\text{CH}} = 10 \text{ MHz}$
		$2/F_{\text{CL}}$	μs	$t_{\text{inst}} = 61.036 \mu\text{s}$, operating at $F_{\text{CL}} = 32.768 \text{ kHz}$

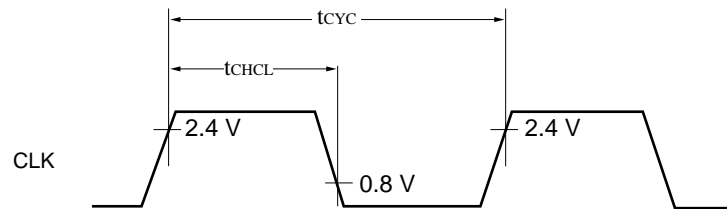
Note: Operating at 10 MHz, the cycle varies with the set execution time.

(5) Clock Output Timing

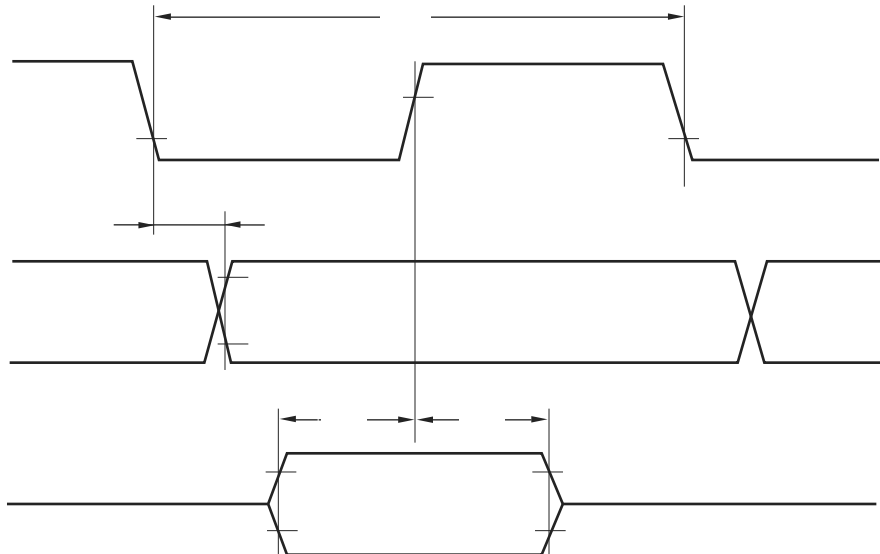
($V_{\text{CC}} = 5.0 \text{ V} \pm 10\%$, $A_{\text{VSS}} = V_{\text{SS}} = 0.0 \text{ V}$, $T_{\text{A}} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$)

Parameter	Symbol	Pin name	Condition	Value		Unit	Remarks
				Min.	Max.		
Cycle time	t_{CYC}	CLK	—	$1/2 t_{\text{inst}}^*$	—	μs	
CLK $\uparrow \rightarrow$ CLK \downarrow	t_{CHCL}	CLK		$1/4 t_{\text{inst}}^* - 70 \text{ ns}$	$1/4 t_{\text{inst}}^*$	μs	

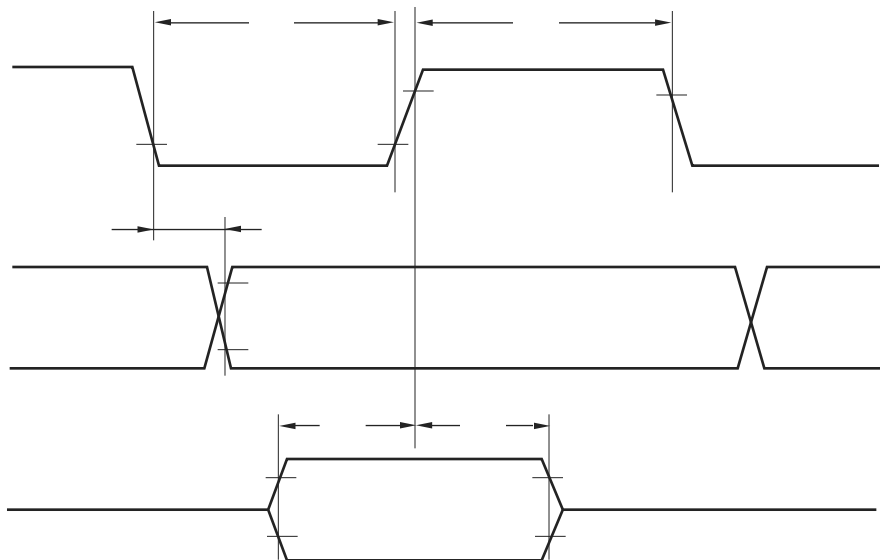
* : For information on t_{inst} , see “(4) Instruction Cycle”.



- Internal shift clock mode

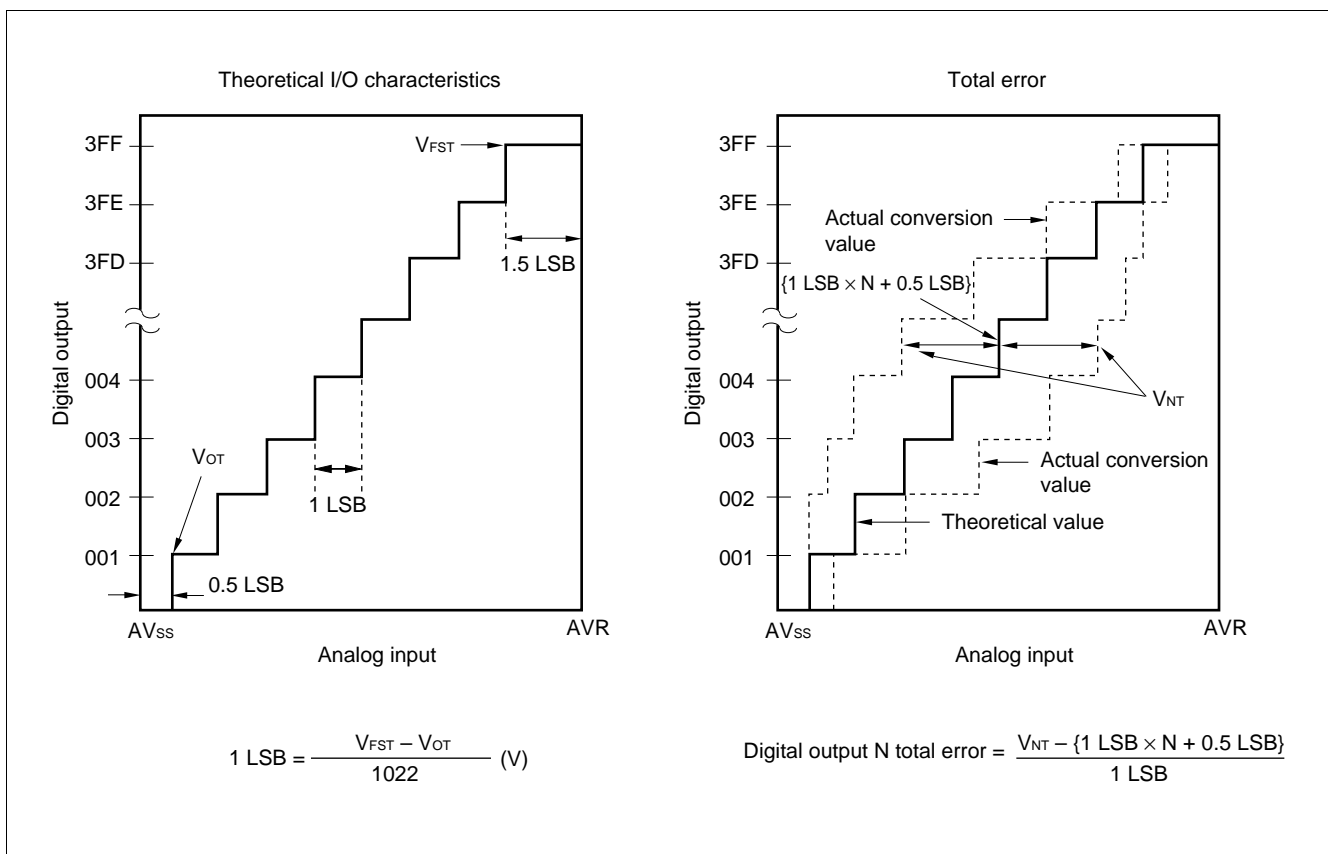


- External shift clock mode



6. A/D Converter Glossary

- Resolution
Analog changes that are identifiable with the A/D converter
- Linearity error
The deviation of the straight line connecting the zero transition point ("00 0000 0000" ↔ "00 0000 0001") with the full-scale transition point ("11 1111 1110" ↔ "11 1111 1111") from actual conversion characteristics
- Differential linearity error
The deviation of input voltage needed to change the output code by 1 LSB from the theoretical value
- Total error (unit: LSB)
The difference between theoretical and actual conversion values caused by the zero transition error, full-scale transition error, linearity error, quantization error, and noise



(Continued)

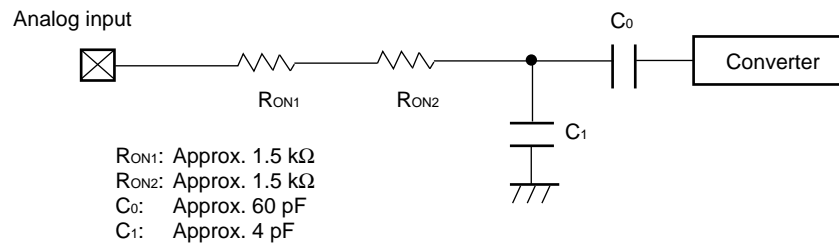
7. Notes on Using A/D Converter

• Input impedance of the analog input pins

The output impedance of the external circuit for the analog input must satisfy the following conditions.

If the output impedance of the external circuit is too high, an analog voltage sampling time might be insufficient (sampling time = 6 μ s at 10 MHz oscillation.) Therefore, it is recommended to keep the output impedance of the external circuit below 10 k Ω .

• Analog input circuit model

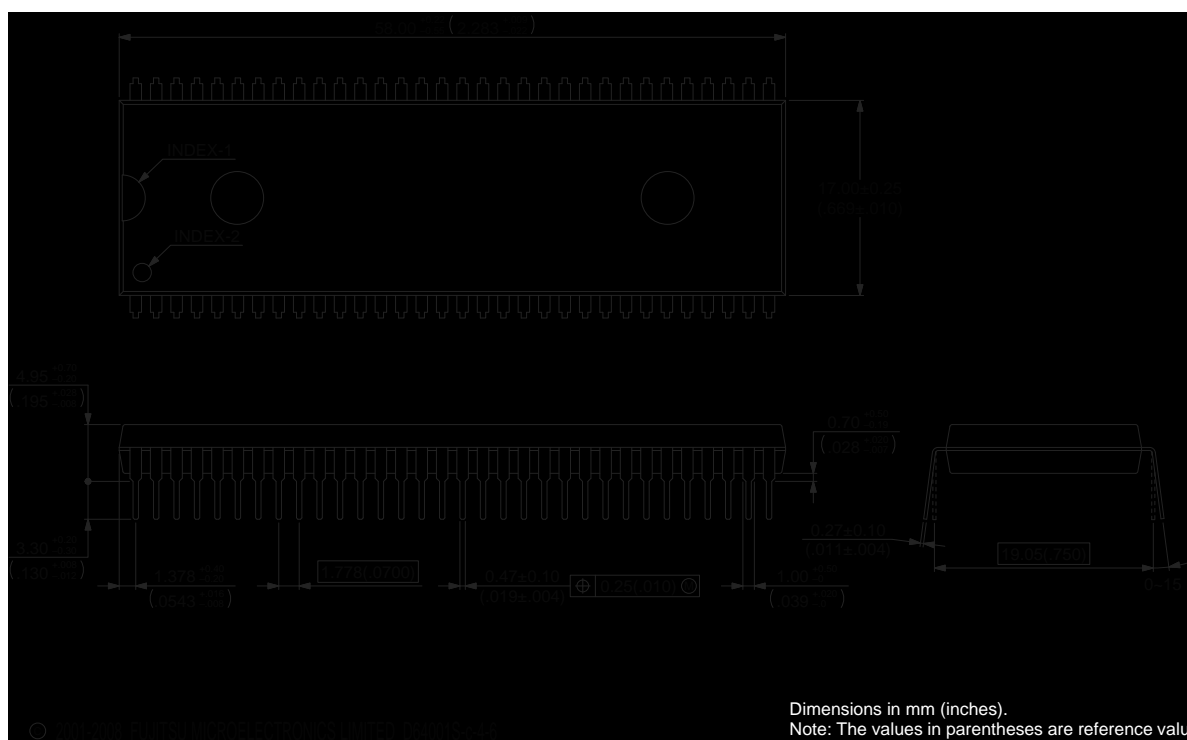
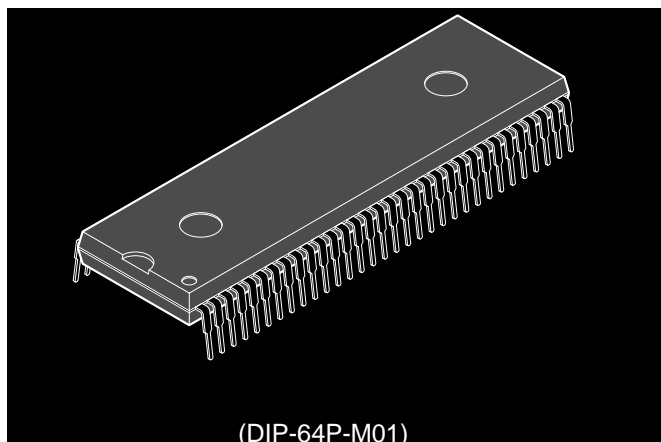


Note: The values mentioned here should be used as a guideline.

• Error

The smaller the $|AVR - AV_{ss}|$, the greater the error would become relatively.

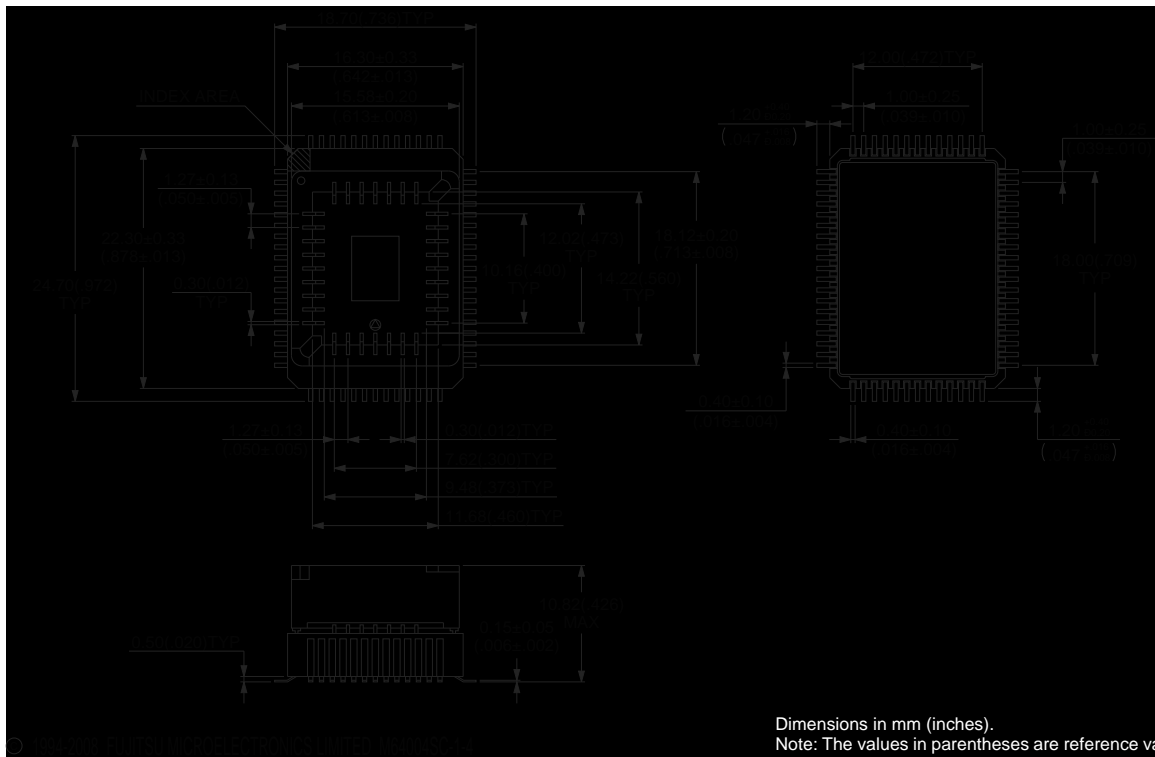
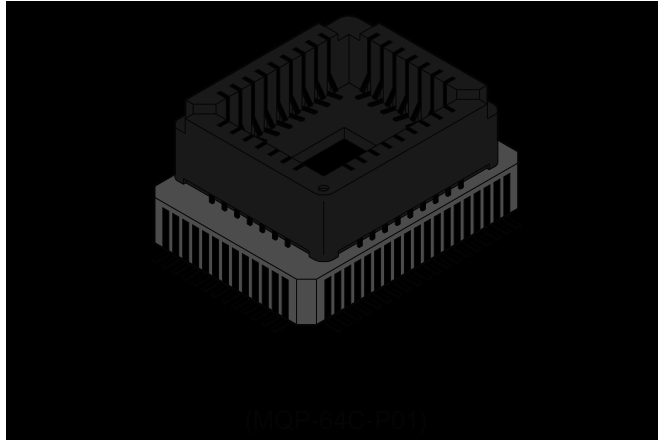
■ PACKAGE DIMENSIONS



Please confirm the latest Package dimension by following URL.
<http://edevic.fujitsu.com/package/en-search/>

(Continued)

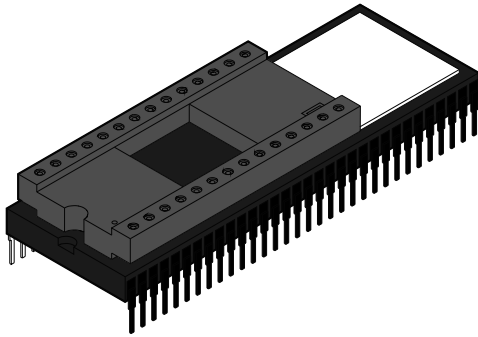
MB89630R Series



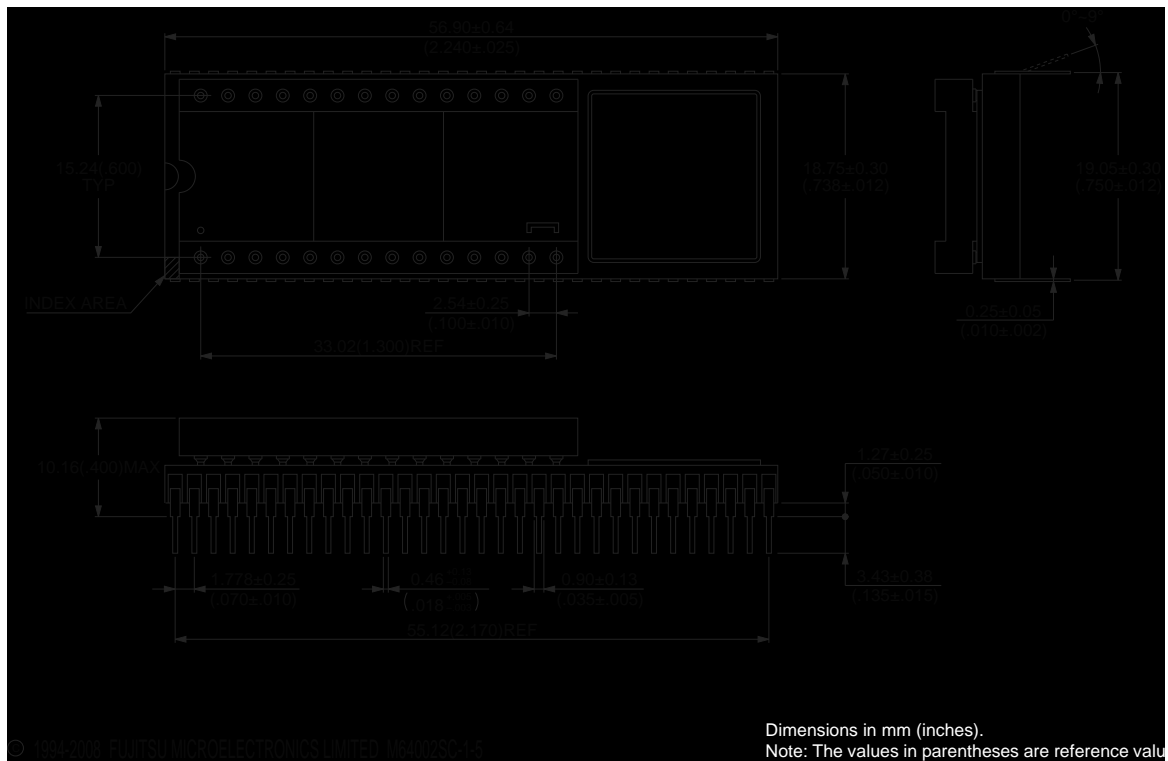
Please confirm the latest Package dimension by following URL.
<http://edevice.fujitsu.com/package/en-search/>

(Continued)

(Continued)



(MDP-64C-P02)



Please confirm the latest Package dimension by following URL.
<http://edevice.fujitsu.com/package/en-search/>

MB89630R Series

■ MAIN CHANGES IN THIS EDITION

Page	Section	Change Results
49	■ MASK OPTIONS	Changed the explanation for "*" in "■ MASK OPTIONS".

The vertical lines marked in the left side of the page show the changes.

MB89630R Series

FUJITSU MICROELECTRONICS LIMITED

Shinjuku Dai-Ichi Seimei Bldg., 7-1, Nishishinjuku 2-chome,

Shinjuku-ku, Tokyo 163-0722, Japan

Tel: +81-3-5322-3329

<http://jp.fujitsu.com/fml/en/>

For further information please contact:

North and South America

FUJITSU MICROELECTRONICS AMERICA, INC.

1250 E. Arques Avenue, M/S 333

Sunnyvale, CA 94085-5401, U.S.A.

Tel: +1-408-737-5600 Fax: +1-408-737-5999

<http://www.fma.fujitsu.com/>

Asia Pacific

FUJITSU MICROELECTRONICS ASIA PTE. LTD.

151 Lorong Chuan,

#05-08 New Tech Park 556741 Singapore

Tel : +65-6281-0770 Fax : +65-6281-0220

<http://www.fmal.fujitsu.com/>

Europe

FUJITSU MICROELECTRONICS EUROPE GmbH

Pittlerstrasse 47, 63225 Langen, Germany

Tel: +49-6103-690-0 Fax: +49-6103-690-122

<http://emea.fujitsu.com/microelectronics/>

FUJITSU MICROELECTRONICS SHANGHAI CO., LTD.

Rm. 3102, Bund Center, No.222 Yan An Road (E),

Shanghai 200002, China

Tel : +86-21-6146-3688 Fax : +86-21-6335-1605

<http://cn.fujitsu.com/fmc/>

Korea

FUJITSU MICROELECTRONICS KOREA LTD.

206 Kosmo Tower Building, 1002 Daechi-Dong,

Gangnam-Gu, Seoul 135-280, Republic of Korea

Tel: +82-2-3484-7100 Fax: +82-2-3484-7111

<http://kr.fujitsu.com/fmk/>

FUJITSU MICROELECTRONICS PACIFIC ASIA LTD.

10/F., World Commerce Centre, 11 Canton Road,

Tsimshatsui, Kowloon, Hong Kong

Tel : +852-2377-0226 Fax : +852-2376-3269

<http://cn.fujitsu.com/fmc/en/>

Specifications are subject to change without notice. For further information please contact each office.

All Rights Reserved.

The contents of this document are subject to change without notice.

Customers are advised to consult with sales representatives before ordering.

The information, such as descriptions of function and application circuit examples, in this document are presented solely for the purpose of reference to show examples of operations and uses of FUJITSU MICROELECTRONICS device; FUJITSU MICROELECTRONICS does not warrant proper operation of the device with respect to use based on such information. When you develop equipment incorporating the device based on such information, you must assume any responsibility arising out of such use of the information.

FUJITSU MICROELECTRONICS assumes no liability for any damages whatsoever arising out of the use of the information.

Any information in this document, including descriptions of function and schematic diagrams, shall not be construed as license of the use or exercise of any intellectual property right, such as patent right or copyright, or any other right of FUJITSU MICROELECTRONICS or any third party or does FUJITSU MICROELECTRONICS warrant non-infringement of any third-party's intellectual property right or other right by using such information. FUJITSU MICROELECTRONICS assumes no liability for any infringement of the intellectual property rights or other rights of third parties which would result from the use of information contained herein.

The products described in this document are designed, developed and manufactured as contemplated for general use, including without limitation, ordinary industrial use, general office use, personal use, and household use, but are not designed, developed and manufactured as contemplated (1) for use accompanying fatal risks or dangers that, unless extremely high safety is secured, could have a serious effect to the public, and could lead directly to death, personal injury, severe physical damage or other loss (i.e., nuclear reaction control in nuclear facility, aircraft flight control, air traffic control, mass transport control, medical life support system, missile launch control in weapon system), or (2) for use requiring extremely high reliability (i.e., submersible repeater and artificial satellite).

Please note that FUJITSU MICROELECTRONICS will not be liable against you and/or any third party for any claims or damages arising in connection with above-mentioned uses of the products.

Any semiconductor devices have an inherent chance of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

Exportation/release of any products described in this document may require necessary procedures in accordance with the regulations of the Foreign Exchange and Foreign Trade Control Law of Japan and/or US export control laws.

The company names and brand names herein are the trademarks or registered trademarks of their respective owners.